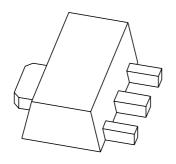
## DISCRETE SEMICONDUCTORS

## DATA SHEET



# PXT2907A PNP switching transistor

Product data sheet Supersedes data of 2002 Mar 20 2004 Dec 09



## **PNP** switching transistor

**PXT2907A** 

## **FEATURES**

- High current (max. 600 mA)
- Low voltage (max. 60 V).

## **APPLICATIONS**

• Switching and linear amplification.

## **DESCRIPTION**

PNP switching transistor in a SOT89 plastic package. NPN complement: PXT2222A.

## **MARKING**

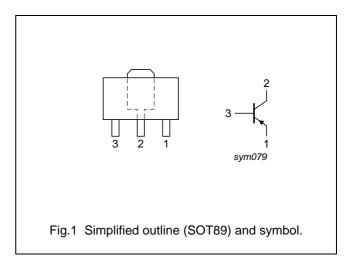
TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PXT2907A	*2F

## Note

- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
  - \* = W: Made in China.

## **PINNING**

PIN	DESCRIPTION
1	emitter
2	collector
3	base



## **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE			
TIPE NOWBER	NAME DESCRIPTION		VERSION	
PXT2907A	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89	

## PNP switching transistor

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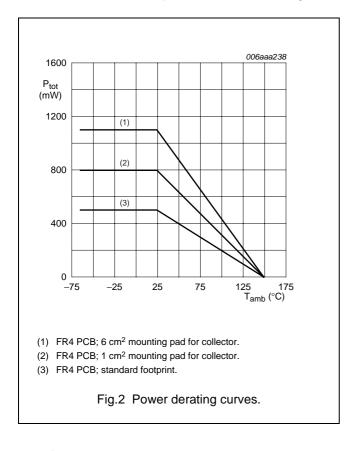
## **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-60	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-5	V
I <sub>C</sub>	collector current (DC)		-	-600	mA
I <sub>CM</sub>	peak collector current		_	-800	mA
I <sub>BM</sub>	peak base current		-	-200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
		note 1	_	0.5	W
		note 2	_	0.8	W
		note 3	_	1.1	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

## **Notes**

- 1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
- 2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.
- 3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm<sup>2</sup>.



## PNP switching transistor

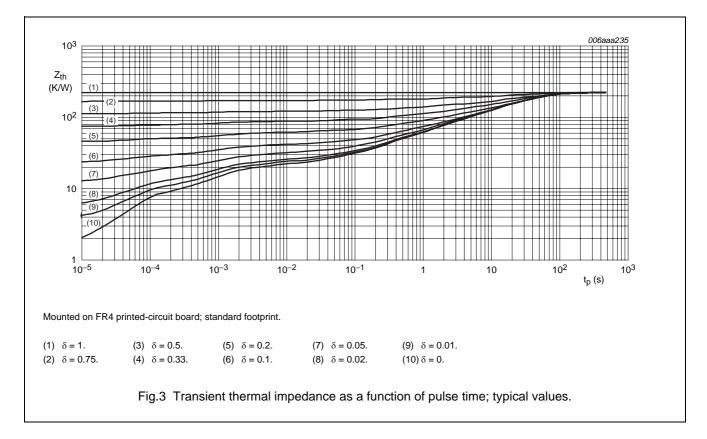
**PXT2907A** 

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to	in free air		
	ambient	note 1	250	K/W
		note 2	156	K/W
		note 3	113	K/W
R <sub>th(j-s)</sub>	thermal resistance from junction to soldering point		30	K/W

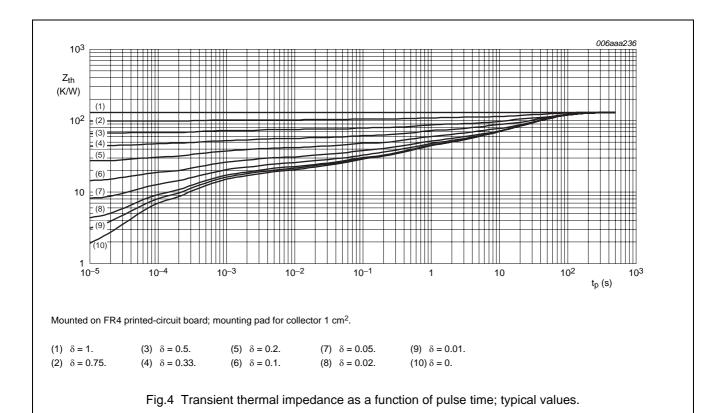
#### **Notes**

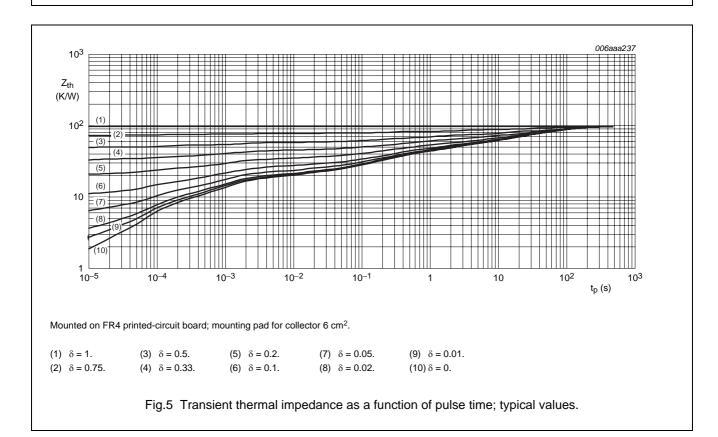
- 1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
- 2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.
- 3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm<sup>2</sup>.



## PNP switching transistor

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## PNP switching transistor

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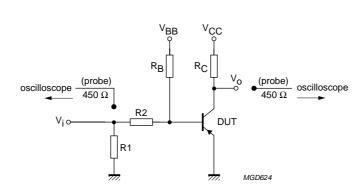
## **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$I_E = 0 \text{ A}; V_{CB} = -50 \text{ V}$	_	-10	nA
		$I_E = 0 \text{ A}; V_{CB} = -50 \text{ V}; T_{amb} = 125 ^{\circ}\text{C}$	_	-10	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$I_C = 0 \text{ A}; V_{EB} = -5 \text{ V}$	_	-50	nA
h <sub>FE</sub>	DC current gain	$I_C = -0.1 \text{ mA}; V_{CE} = -1 \text{ V}$	75	_	
		$I_C = -1 \text{ mA}; V_{CE} = -1 \text{ V}$	100	_	
		$I_C = -10 \text{ mA}; V_{CE} = -1 \text{ V}$	100	_	
		$I_C = -150 \text{ mA}; V_{CE} = -2 \text{ V}$	100	300	
ı		$I_C = -500 \text{ mA}; V_{CE} = -10 \text{ V}$	50	_	
V <sub>CEsat</sub>	collector-emitter saturation	$I_C = -150 \text{ mA}; I_B = -15 \text{ mA}$	_	-400	mV
voltage	voltage	$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	-1.6	V
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_C = -150 \text{ mA}; I_B = -15 \text{ mA}$	_	-1.3	V
		$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	-2.6	V
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0 \text{ A}; V_{CB} = -10 \text{ V}; f = 1 \text{ MHz}$	_	8	pF
C <sub>e</sub>	emitter capacitance	$I_C = i_c = 0 \text{ A}; V_{EB} = -500 \text{ mV};$ f = 1 MHz	_	35	pF
f <sub>T</sub>	transition frequency	$I_C = -20 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 100 MHz	200	_	MHz
Switching t	imes (between 10% and 90% leve	ls); (see Fig.6)		•	
t <sub>on</sub>	turn-on time	$I_{Con} = -150 \text{ mA}; I_{Bon} = -15 \text{ mA};$	_	40	ns
t <sub>d</sub>	delay time	I <sub>Boff</sub> = 15 mA	_	12	ns
t <sub>r</sub>	rise time	1	_	30	ns
t <sub>off</sub>	turn-off time	1	_	365	ns
t <sub>s</sub>	storage time	1	_	300	ns
t <sub>f</sub>	fall time	1	_	65	ns

## PNP switching transistor

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 $V_i = -9.5$  V; T = 500  $\mu s;$   $t_p = 10$   $\mu s;$   $t_r = t_f \leq 3$  ns.

R1 = 68  $\Omega$ ; R2 = 325  $\Omega$ ; R<sub>B</sub> = 325  $\Omega$ ; R<sub>C</sub> = 160  $\Omega$ .

 $V_{BB}$  = 3.5 V;  $V_{CC}$  = –29.5 V.

Oscilloscope input impedance  $Z_i$  = 50  $\Omega$ .

Fig.6 Test circuit for switching times.

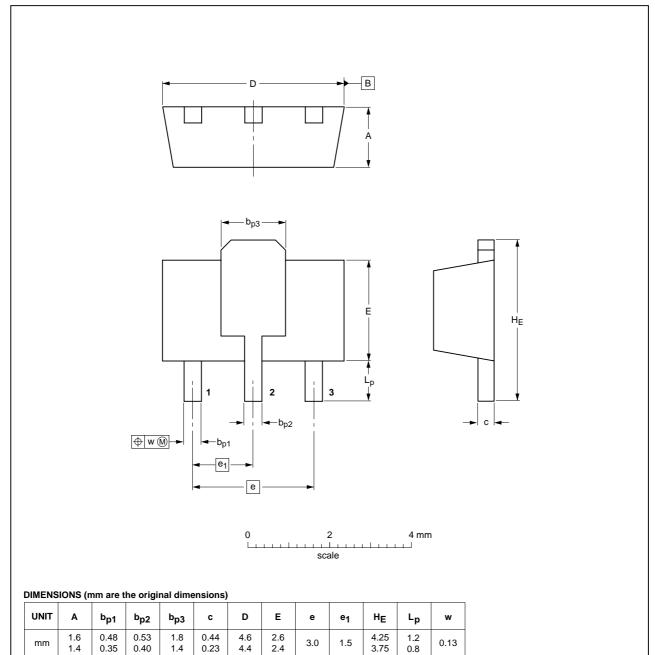
## PNP switching transistor

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## **PACKAGE OUTLINE**

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



OUTLINE	REFERENCES		EUROPEAN	ICCUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT89		TO-243	SC-62			<del>04-08-03</del> 06-03-16

## PNP switching transistor

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#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

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